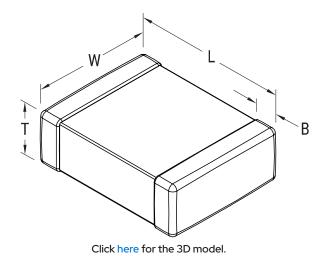


CBR06C100FAGAC

General Information

CBR-SMD RF COG, Ceramic, 10 pF, 1%, 250 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0603



Series	CBR-SMD RF COG	
Style	SMD Chip	
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I	
Features	Ultra High Q, Low ESR, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	5.29 mg	
Notes	Solder Wave or Solder Reflow.	
Shelf Life	78 Weeks	
MSL	1	

10 pF

600

Dimensions	
Chip Size	0603
L	1.6mm +/-0.1mm
W	0.8mm +/-0.1mm
т	0.8mm +/-0.07mm
В	0.4mm +/-0.15mm

	Tolerance	1%
	Voltage DC	250 VDC
n	Dielectric Withstanding Voltage	500 VDC
ı	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
	Dissipation Factor	0.167%
tic Tape	Aging Rate	0% Loss/Decade Hour
	Insulation Resistance	10 GOhms

Specifications

Capacitance

Quality Factor

Packaging Specifications

Packaging Packaging Quantity T&R, 180mm, Plastic Tape 4000

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